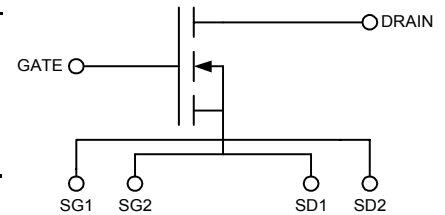


- ◆ N-Channel Enhancement Mode
- ◆ Low  $Q_g$  and  $R_{g}$
- ◆ High  $dv/dt$
- ◆ Nanosecond Switching
- ◆ 50MHz Maximum Frequency

$V_{DSS} = 500 \text{ V}$   
 $I_{D25} = 25 \text{ A}$   
 $R_{DS(on)} = 0.22 \Omega$   
 $P_{DC} = 940 \text{ W}$

Symbol	Test Conditions	Maximum Ratings	
$V_{DSS}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	500	V
$V_{DGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ ; $R_{GS} = 1 \text{ M}\Omega$	500	V
$V_{GS}$	Continuous	$\pm 20$	V
$V_{GSM}$	Transient	$\pm 30$	V
$I_{D25}$	$T_c = 25^\circ\text{C}$	25	A
$I_{DM}$	$T_c = 25^\circ\text{C}$ , pulse width limited by $T_{JM}$	150	A
$I_{AR}$	$T_c = 25^\circ\text{C}$	21	A
$E_{AR}$	$T_c = 25^\circ\text{C}$	30	mJ
$dv/dt$	$I_S \leq I_{DM}$ , $di/dt \leq 100 \text{ A}/\mu\text{s}$ , $V_{DD} \leq V_{DSS}$ , $T_J \leq 150^\circ\text{C}$ , $R_G = 0.2 \Omega$	5	V/ns
	$I_S = 0$	>200	V/ns
$P_{DC}$		940	W
$P_{DHS}$	$T_c = 25^\circ\text{C}$ Derate $3.7 \text{ W}/^\circ\text{C}$ above $25^\circ\text{C}$	425	W
$P_{DAMB}$	$T_c = 25^\circ\text{C}$	4.5	W
$R_{thJC}$		0.16	C/W
$R_{thJHS}$		0.36	C/W



**Features**

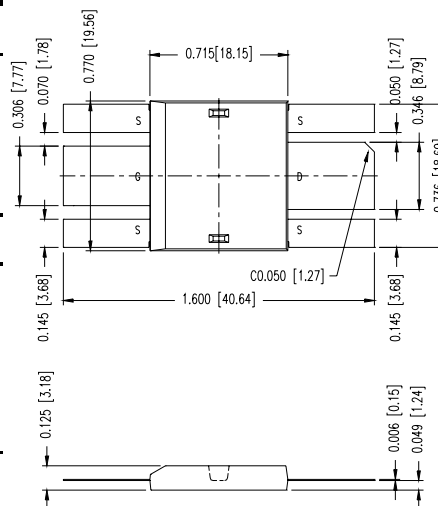
- Isolated Substrate
  - high isolation voltage (>2500V)
  - excellent thermal transfer
  - Increased temperature and power cycling capability
- IXYS advanced low  $Q_g$  process
- Low gate charge and capacitances
  - easier to drive
  - faster switching
- Low  $R_{DS(on)}$
- Very low insertion inductance (<2nH)
- No beryllium oxide (BeO) or other hazardous materials

**Advantages**

- Optimized for RF and high speed switching at frequencies to 50MHz
- Easy to mount—no insulators needed
- High power density

Symbol	Test Conditions	Characteristic Values		
		$T_J = 25^\circ\text{C}$ unless otherwise specified		
		min.	typ.	max.
$V_{DSS}$	$V_{GS} = 0 \text{ V}$ , $I_D = 3 \text{ ma}$	500		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 4 \text{ ma}$	2.5		5.5 V
$I_{GSS}$	$V_{GS} = \pm 20 \text{ V}_{DC}$ , $V_{DS} = 0$			$\pm 100 \text{ nA}$
$I_{DSS}$	$V_{DS} = 0.8 V_{DSS}$ , $T_J = 25^\circ\text{C}$ $V_{GS} = 0$ , $T_J = 125^\circ\text{C}$			50 $\mu\text{A}$
				1 mA
$R_{DS(on)}$	$V_{GS} = 15 \text{ V}$ , $I_D = 0.5 I_{D25}$ Pulse test, $t \leq 300 \mu\text{s}$ , duty cycle $d \leq 2\%$			0.22 $\Omega$
$g_{fs}$	$V_{DS} = 15 \text{ V}$ , $I_D = 0.5 I_{D25}$ , pulse test		17	S
$T_J$		-55		+175 $^\circ\text{C}$
$T_{JM}$			175	$^\circ\text{C}$
$T_{stg}$		-55		+175 $^\circ\text{C}$
$T_L$	1.6mm (0.063 in) from case for 10 s		300	$^\circ\text{C}$
<b>Weight</b>			3	g

Symbol	Test Conditions	Characteristic Values		
		(T <sub>J</sub> = 25°C unless otherwise specified)		
		min.	typ.	max.
<b>R<sub>G</sub></b>			0.3	Ω
<b>C<sub>iss</sub></b>			2000	pF
<b>C<sub>oss</sub></b>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 0.8 V <sub>DSS(max)</sub> , f = 1 MHz		200	pF
<b>C<sub>rss</sub></b>			45	pF
<b>C<sub>stray</sub></b>	Back Metal to any Pin		33	pF
<b>T<sub>d(on)</sub></b>			5	ns
<b>T<sub>on</sub></b>	V <sub>GS</sub> = 15 V, V <sub>DS</sub> = 0.8 V <sub>DSS</sub> I <sub>D</sub> = 0.5 I <sub>DM</sub>		3	ns
<b>T<sub>d(off)</sub></b>	R <sub>G</sub> = 0.2 Ω (External)		5	ns
<b>T<sub>off</sub></b>			8	ns
<b>Q<sub>g(on)</sub></b>			77	nC
<b>Q<sub>gs</sub></b>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 0.5 V <sub>DSS</sub> I <sub>D</sub> = 0.5 I <sub>D25</sub>		21	nC
<b>Q<sub>gd</sub></b>			40	nC



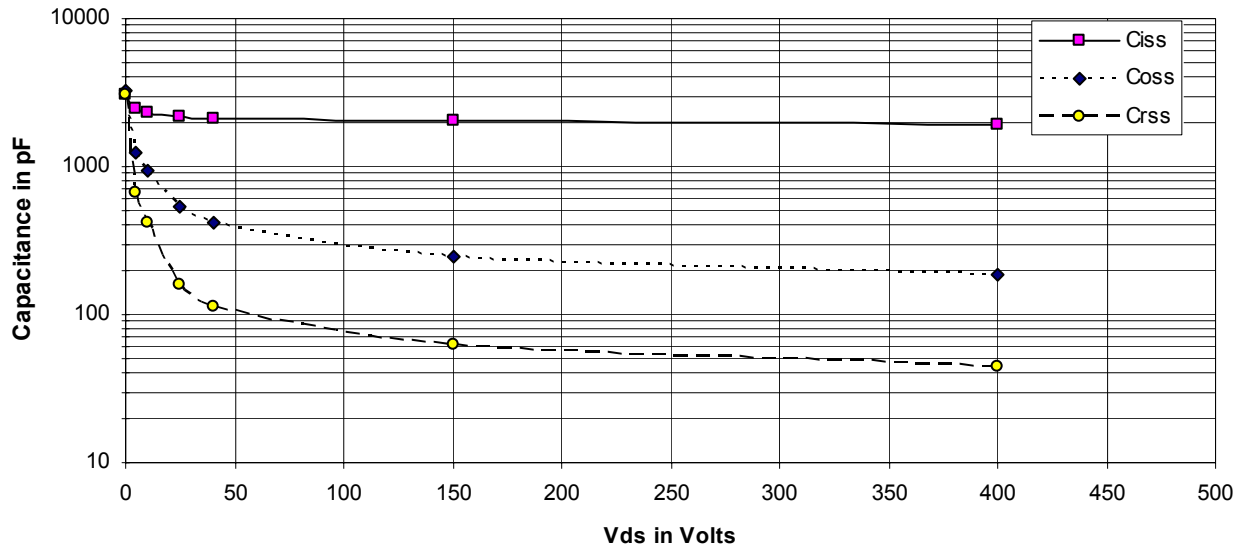
Symbol	Test Conditions	Characteristic Values		
		(T <sub>J</sub> = 25°C unless otherwise specified)		
		min.	typ.	max.
<b>I<sub>S</sub></b>	V <sub>GS</sub> = 0 V			21 A
<b>I<sub>SM</sub></b>	Repetitive; pulse width limited by T <sub>JM</sub>			150 A
<b>V<sub>SD</sub></b>	I <sub>F</sub> = I <sub>S</sub> , V <sub>GS</sub> = 0 V, Pulse test, t ≤ 300 μs, duty cycle ≤ 2%			1.5 V
<b>T<sub>rr</sub></b>			200	ns
<b>Q<sub>RM</sub></b>	I <sub>F</sub> = I <sub>S</sub> , -di/dt = 100A/μs, V <sub>R</sub> = 100V		0.6	μC
<b>I<sub>RM</sub></b>			15	A

For detailed device mounting and installation instructions, see the “*DE-Series MOSFET Mounting Instructions*” technical note on IXYS RF’s web site at [www.ixysrf.com/Technical\\_Support/App\\_notes.html](http://www.ixysrf.com/Technical_Support/App_notes.html)

IXYS RF reserves the right to change limits, test conditions and dimensions.

IXYS RF MOSFETS are covered by one or more of the following U.S. patents:

4,835,592	4,850,072	4,881,106	4,891,686	4,931,844	5,017,508
5,034,796	5,049,961	5,063,307	5,187,117	5,237,481	5,486,715
5,381,025	5,640,045				



375-501N21A Capacitances vs Vds

**501N21A DE-SERIES SPICE Model** (Preliminary)

The DE-SERIES SPICE Model is illustrated in Figure 1. The model is an expansion of the SPICE level 3 MOSFET model. It includes the stray inductive terms  $L_G$ ,  $L_S$  and  $L_D$ .  $R_d$  is the  $R_{DS(ON)}$  of the device,  $R_{ds}$  is the resistive leakage term. The output capacitance,  $C_{OSS}$ , and reverse transfer capacitance,  $C_{RSS}$  are modeled with reversed biased diodes. This provides a varactor type response necessary for a high power device model. The turn on delay and the turn off delay are adjusted via  $R_{on}$  and  $R_{off}$ .

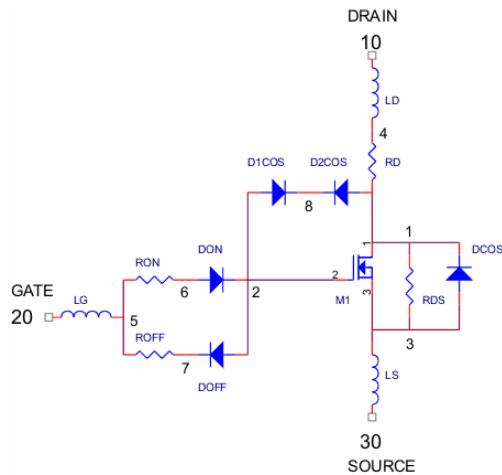


Figure 1 DE-SERIES SPICE Model

This SPICE model may be downloaded as a text file from the DEI web site at [www.directedenergy.com/spice.htm](http://www.directedenergy.com/spice.htm)

Net List:

```
.SUBCKT 501N21A 10 20 30
* TERMINALS: D G S
* 500 Volt 21 Amp 0.22 ohm N-Channel Power MOSFET
* REV.A 01-09-02
M1 1 2 3 3 DMOS L=1U W=1U
RON 5 6 0.3
DON 6 2 D1
ROF 5 7 .1
DOF 2 7 D1
D1CRS 2 8 D2
D2CRS 1 8 D2
CGS 2 3 2.6N
RD 4 1 0.22
DCOS 3 1 D3
RDS 1 3 5.0MEG
LS 3 30 .5N
LD 10 4 1N
LG 20 5 1N
.MODEL DMOS NMOS (LEVEL=3 VTO=3.0 KP=3.8)
.MODEL D1 D (IS=.5F CJO=1P BV=100 M=.5 VJ=.6 TT=1N)
.MODEL D2 D (IS=.5F CJO=400P BV=1000 M=.4 VJ=.6 TT=400N RS=10M)
.MODEL D3 D (IS=.5F CJO=900P BV=1000 M=.3 VJ=.4 TT=400N RS=10M)
.ENDS
```

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